HEAT CONDUCTIVE SUBSTRATE MOUNTED IN PC BOARD HOLE FOR TRANSFERRING HEAT FROM IC TO HEAT SINK

ABSTRACT OF THE DISCLOSURE

A heat conductive substrate (50) is mounted within a through-opening (60) of a printed circuit board (52). An integrated circuit (42) then is mounted to one side (64) of the heat conductive substrate, while a heat sink (90) is fixed in thermal contact to the other side (66) of the substrate. There is no direct thermal contact between the IC and the PC board. The substrate is mounted to an undersurface (70) of the PC board and concentrically spaced from the PC board within the opening (60). An air gap (80) occurs between the substrate and the PC board within the opening to substantially reduce heat conductivity into the PC board.

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